

# SMB1N-720

- Infrared High Power LED
- 720 nm, 170 mW
- SMD package, PA9T
- Dimension: 5.0 x 5.2 x 1.0 mm
- Viewing Angle: 130°

## Description





Rev A1

SMB1N-720 is a surface mount AlGaAs High Power LED with a typical peak wavelength of 720 nm and radiation of 170 mW. It comes in SMD package (PA9T) with silver plated soldering pads (lead free solderable), copper heat sink, and molded with silicone resin.

### Maximum Ratings (T<sub>CASE</sub>=25°C)

Deremeter	0	Va	1114		
Parameter	Symbol	Min.	Max.	Unit	
Power Dissipation	PD		1700	mW	
Forward Current	IF		600	mA	
Pulse Forward Current *1	IFP		2000	mA	
Reverse Voltage	VF		5	V	
Thermal Resistance	RTHJA		10	K/W	
Junction Temperature	$T_J$		120	°C	
Operating Temperature	T <sub>CASE</sub>	- 40	+ 100	°C	
Storage Temperature	Tstg	- 40	+ 100	°C	
Lead Solder Temperature *2	T <sub>SLD</sub>		+ 250	°C	

\*1 duty=1%, pulse width = 10  $\mu$ s

\*2 must be completed within 5 seconds

#### Electro-Optical Characteristics $(T_{CASE}=25^{\circ}C)$

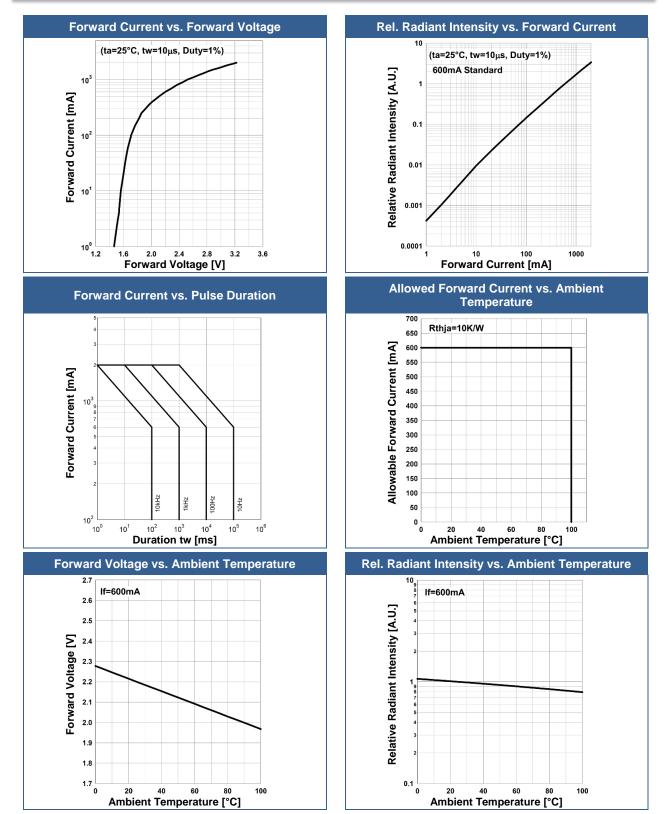
Parameter	Symbol	Conditions	Min.	Values Typ.	Max.	Unit	
Peak Wavelength	λP	I⊧=600mA	710		730	nm	
Half Width	$\Delta \lambda$	I⊧=600mA		23		nm	
Forward Voltage	VF	I⊧=600mA		2.2	2.8	V	
Forward voltage	VFP	IFP=2A		3.2		v	
Radiated Power *1	Po	I⊧=600mA	140	170		mW	
Radiated Fower	PO	IFP=2A		570		TTIVV	
Radiant Intensity *2	le	I⊧=600mA		56		mW/sr	
	IE	IFP=2A		190		11100/51	
Viewing Angle	φ	I <sub>F</sub> =100mA		130		deg.	
Rise Time	t <sub>R</sub>	I⊧=600mA		10		ns	
Fall Time	t⊢	I⊧=600mA		20		ns	

\*1 measured by S3584-08

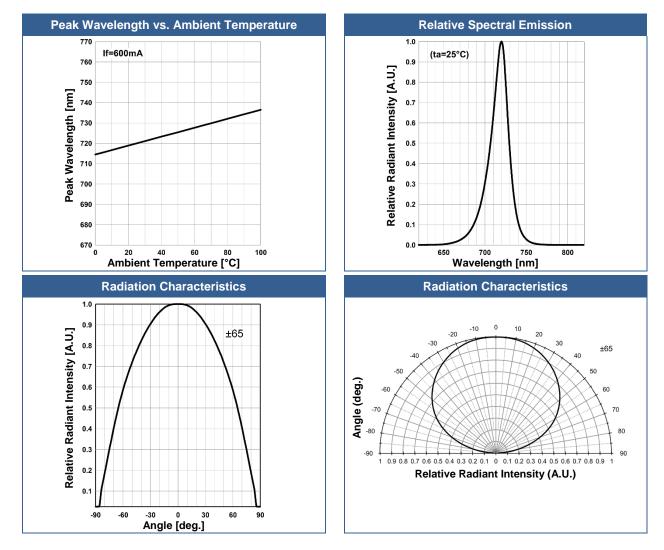
\*2 measured by CIE127-2007 Condition B



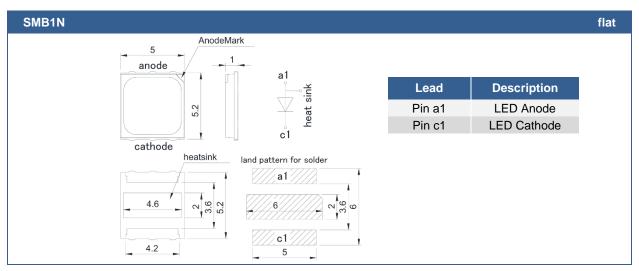
# Typical Performance Curves







# **Outline Dimensions**



All Dimensions in mm



### Precautions

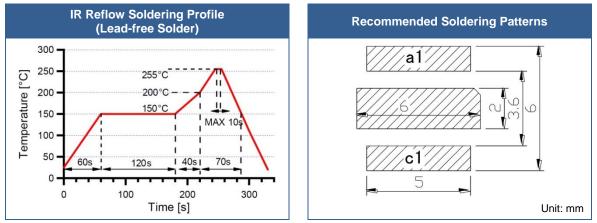
#### Soldering:

- Do avoid overheating of the LED
- Do avoid electrostatic discharge (ESD)
- Do avoid mechanical stress, shock, and vibration
- Do only use non-corrosive flux
- Do not apply current to the LED until it has cooled down to room temperature after soldering

#### **Recommended soldering conditions:**

This LED is designed to be reflow soldered on to a PCB. If dip soldered or hand soldered, its reliability cannot be guarantee.

Nitrogen reflow soldering is recommended. Air flow soldering conditions can cause optical degradation, caused by heat and/or atmosphere.



Above table specifies the maximum allowed duration and temperature during soldering. It is strongly advised to perform soldering at the shortest time and lowest temperature possible.

#### **Cleaning:**

#### Cleaning with isopropyl alcohol, propanol, or ethyl alcohol is recommended

DO NOT USE acetone, chloroseen, trichloroethylene, or MKS DO NOT USE ultrasonic cleaners

#### **Static Electricity:**

**LEDs are sensitive to electrostatic discharge (ESD)**. Precautions against ESD must be taken when handling or operating these LEDs. Surge voltage or electrostatic discharge can result in complete failure of the device.

#### **Radiation:**

During operation these LEDs do emit **high intensity light**, which is hazardous to skin and eyes, and may cause cancer. Do avoid exposure to the emitted light. **Protective glasses are recommended**. It is further advised to attach a warning label on products/systems.

#### **Operation:**

#### Do only operate LEDs with a current source.

Running these LEDs from a voltage source will result in complete failure of the device. Current of a LED is an exponential function of the voltage across it. Usage of current regulated drive circuits is mandatory.



# **Revisions History**

Rel.	Rel. Date	Chapter	Modification	Page
A1	13.02.2020	-	released	-

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The above specifications are for reference purpose only and subjected to change without prior notice